



SOT1369-4

HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

23 November 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-10-2020
Manufacturer package code	98ASA00913D

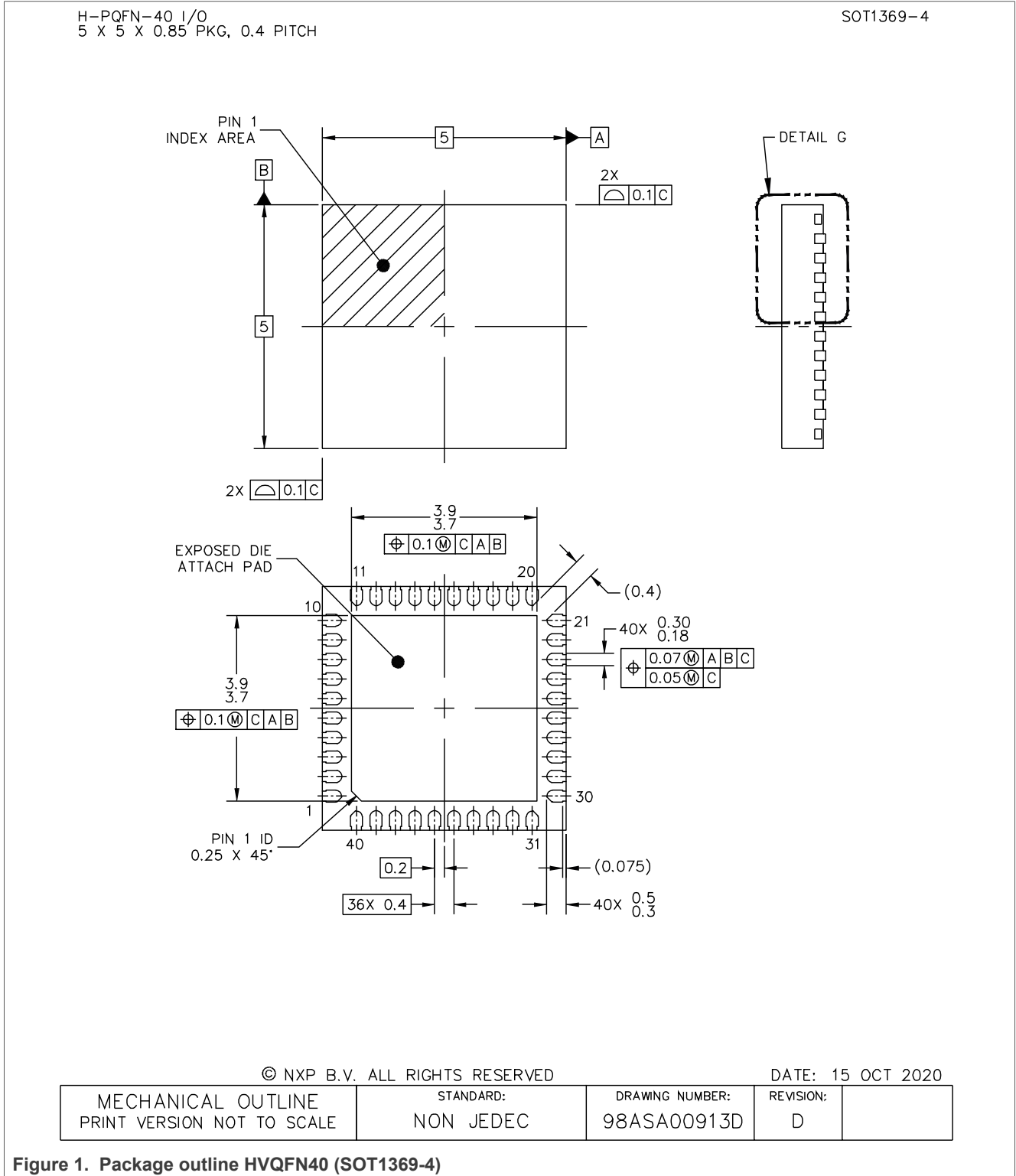
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
seated height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	40	-	



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2 Package outline



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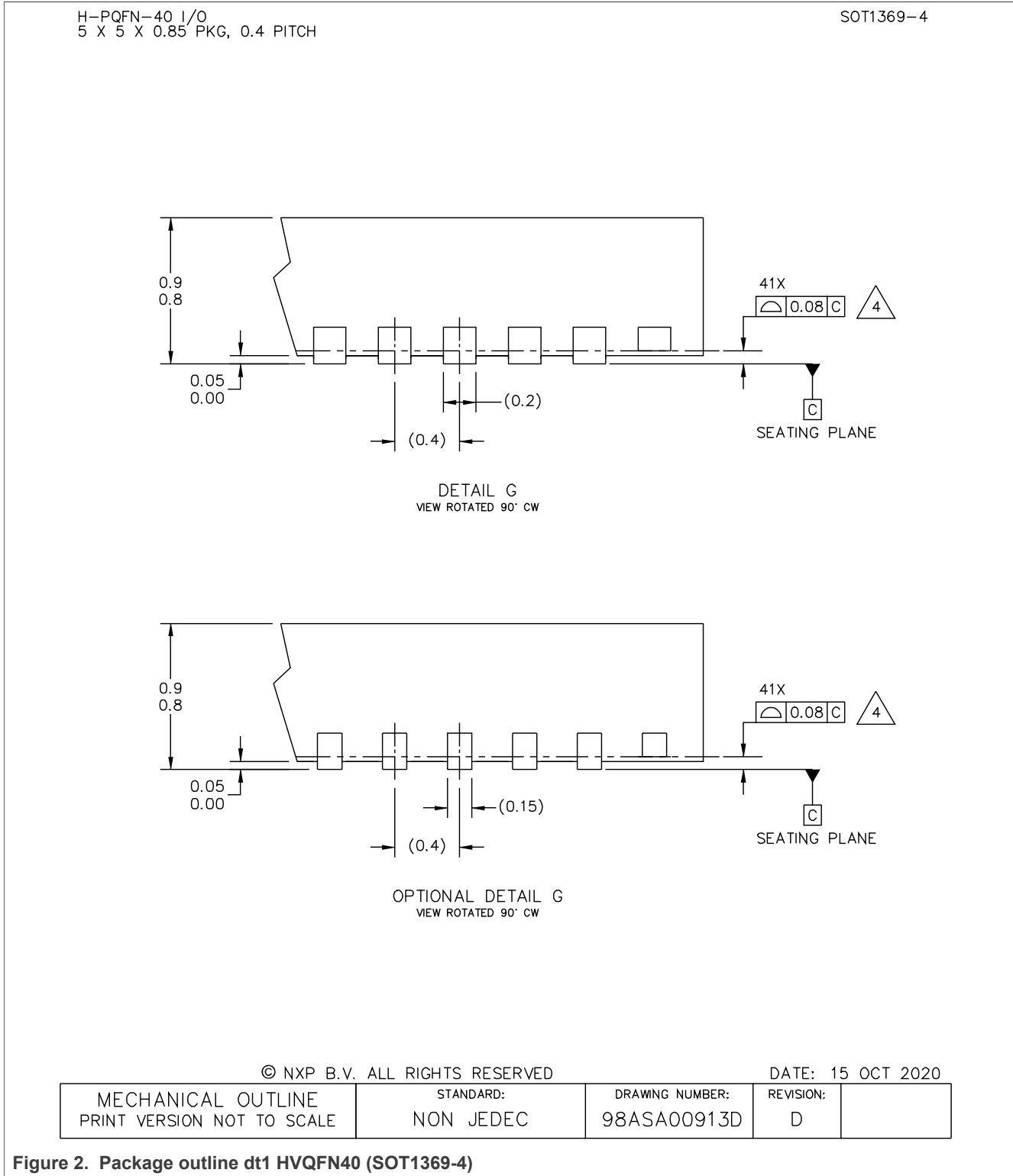
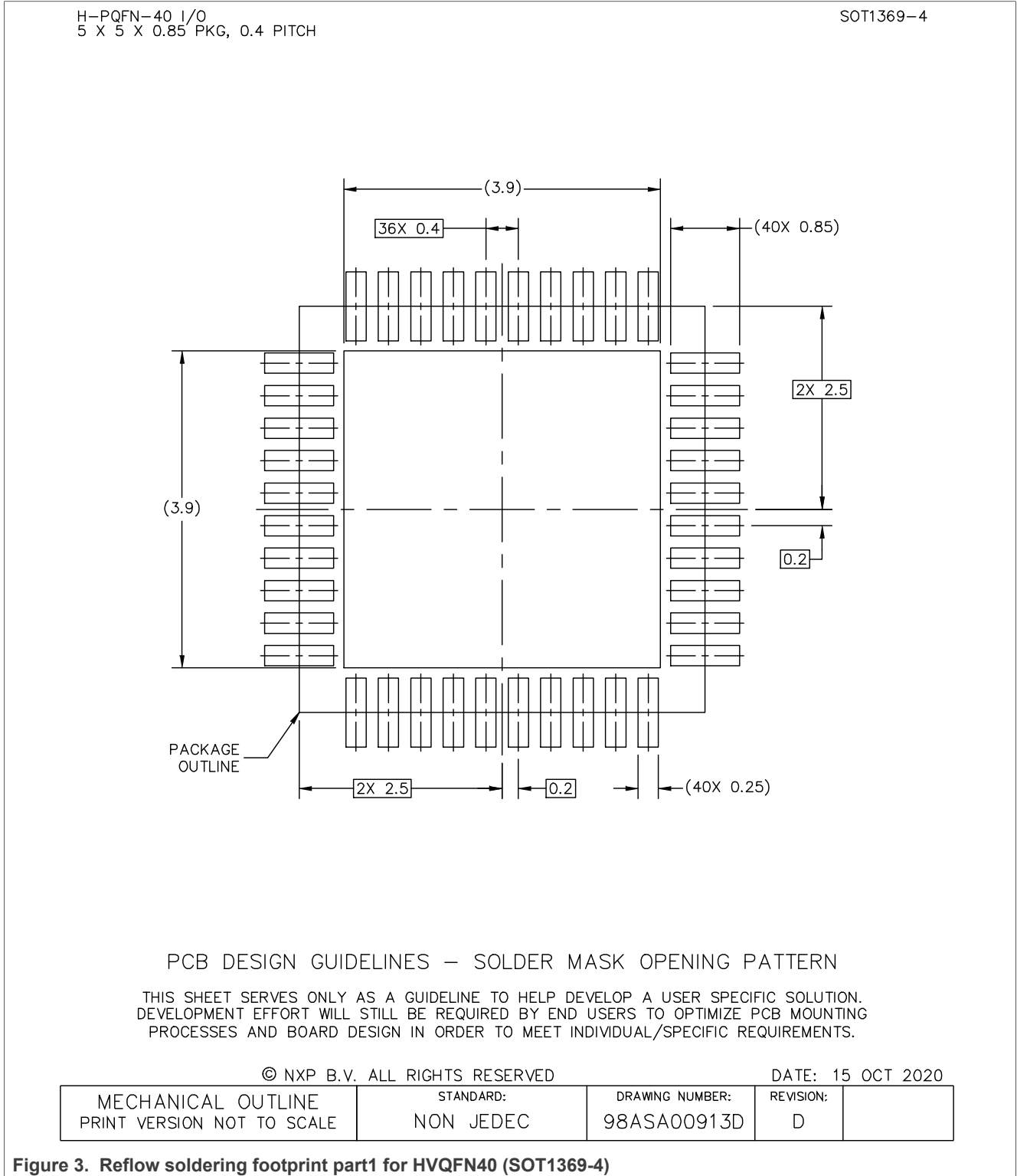


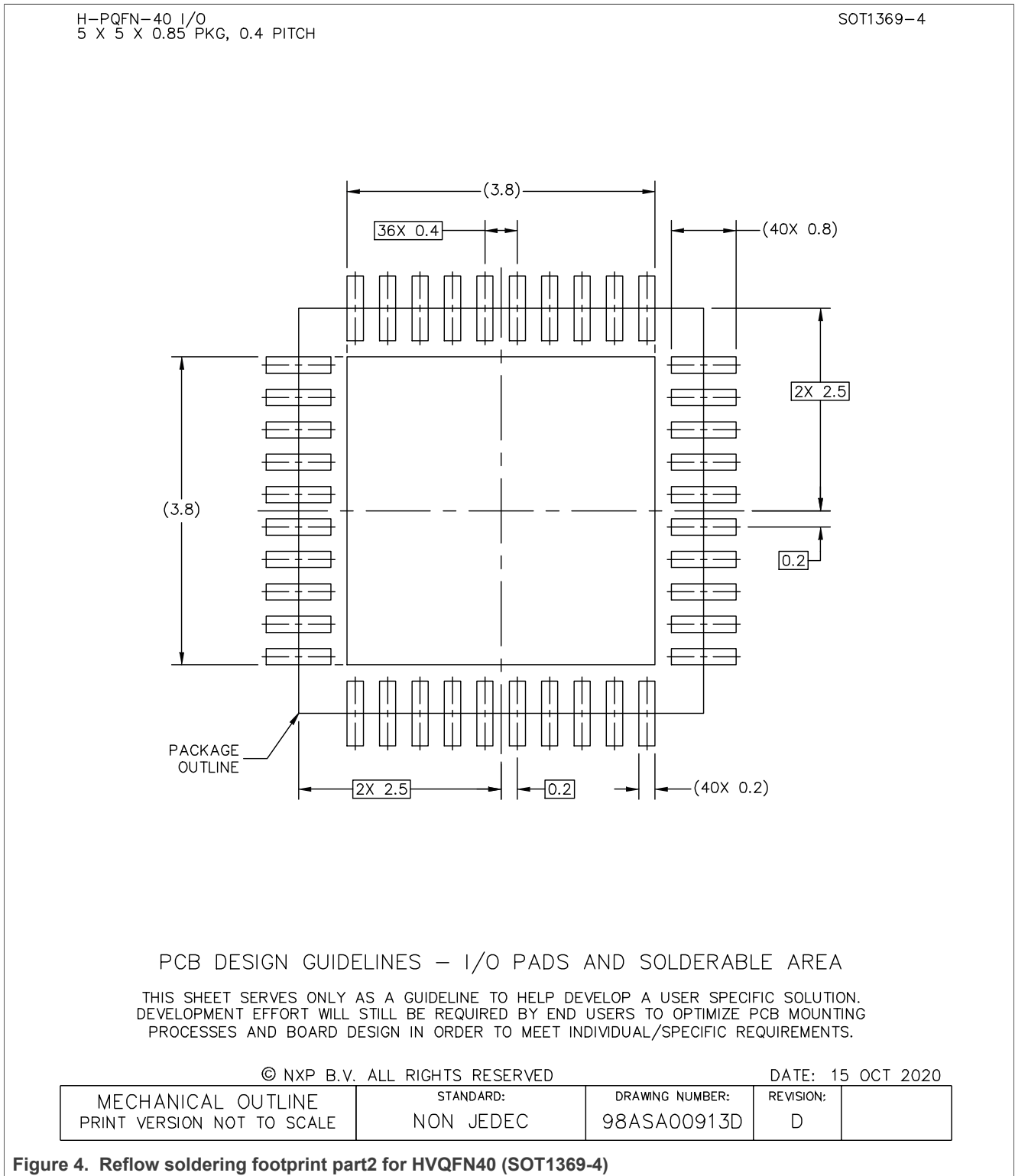
Figure 2. Package outline dt1 HVQFN40 (SOT1369-4)

HVQFN40, plastic, thermally enhanced very thin quad flat, non-ledged package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body

3 Soldering



HVQFN40, plastic, thermally enhanced very thin quad flat, non-leaded package; 40 terminals; 0.4 mm pitch; 5 mm x 5 mm x 0.85 mm body



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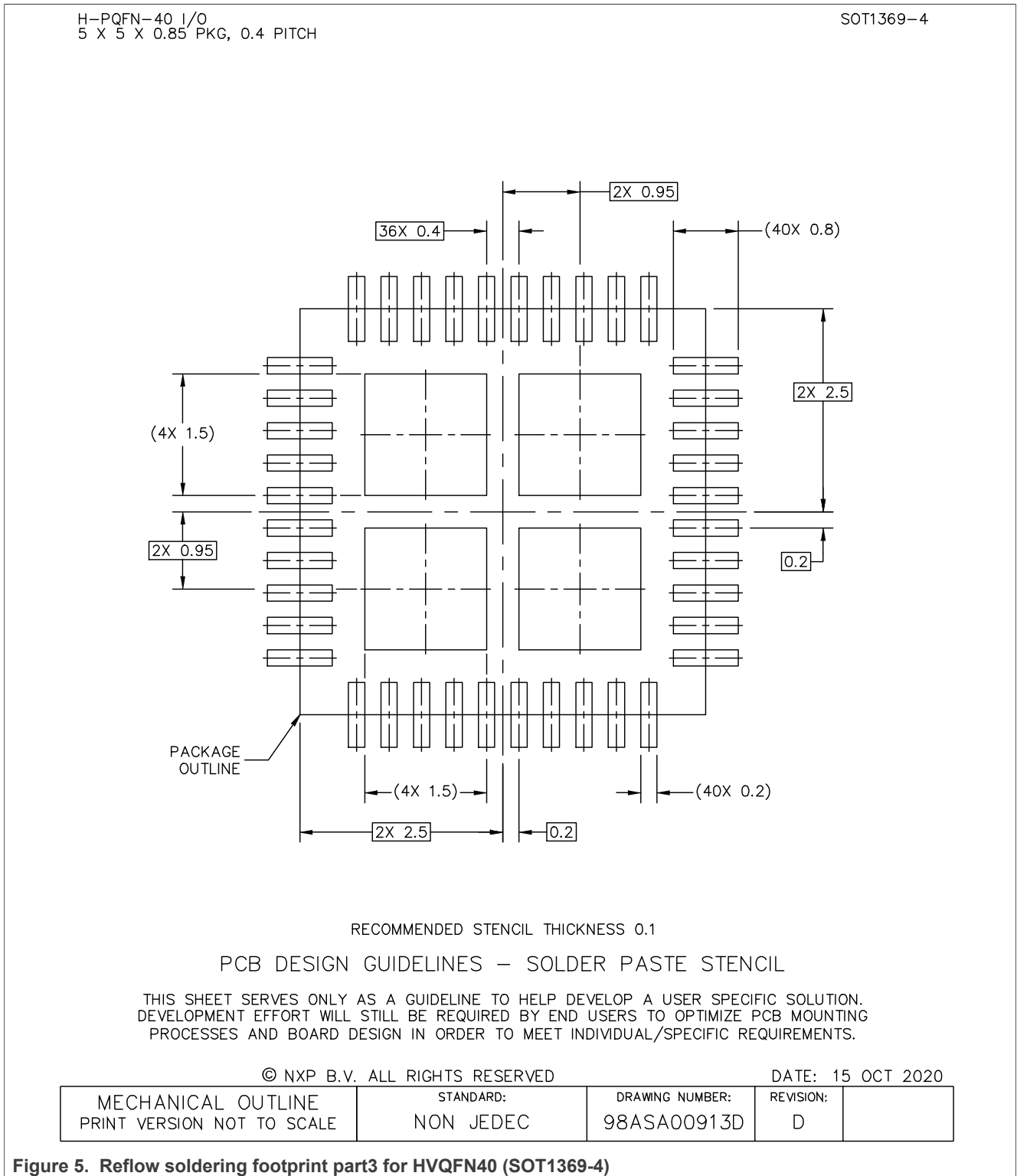



Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT1369-4)

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H-PQFN-40 I/O
5 X 5 X 0.85 PKG, 0.4 PITCH

SOT1369-4

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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DATE: 15 OCT 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA00913D	REVISION: D	
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Figure 6. Package outline note HVQFN40 (SOT1369-4)

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4 Legal information

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